

## 1. Product information

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

|                |                |
|----------------|----------------|
| Part Number :  | CJAC1214M03    |
| Package Type : | PDFNWB5x6-8L-A |

## 2. MATERIAL ANALYSIS DATA SHEET

| Material      | Composition           | CAS No.     | % of weight | % of weight total |
|---------------|-----------------------|-------------|-------------|-------------------|
| Wafer         | Silicon               | 7440-21-3   | 100.00%     | 3.2067%           |
| Lead Frame    | Copper                | 7440-50-8   | 97.3317%    | 38.058%           |
|               | Fe                    | 7439-89-6   | 2.4123%     |                   |
|               | P                     | 7723-14-0   | 0.079%      |                   |
|               | Zn                    | 7440-66-6   | 0.143%      |                   |
|               | Pb                    | 7439-92-1   | 0.029%      |                   |
|               | Ag                    | 7440-22-4   | 0.005%      |                   |
| Die Attach    | lead                  | 7439-92-1   | 82.24%      | 19.7461%          |
|               | Rosin, hydrogenated   | 65997-06-0  | 6.73%       |                   |
|               | tin                   | 7440-31-5   | 2.91%       |                   |
|               | Terpineol             | 8000-41-7   | 3.31%       |                   |
|               | [(butoxymethylethoxy) | 55934-93-5  | 3.67%       |                   |
|               | Reaction mass of :12- | 126098-16-6 | 0.61%       |                   |
|               | (Z)-N-methyl-N-(1-    | 110-25-8    | 0.53%       |                   |
| Wire1         | copper                | 7440-50-8   | 99.99%      | 2.4523%           |
|               | others                | /           | 0.01%       |                   |
| Wire2         | Cu                    | 7440-50-8   | 96.80%      | 3.3215%           |
|               | Pd                    | 7440-05-3   | 2.98%       |                   |
|               | Au                    | 7440-57-5   | 0.22%       |                   |
| Mold Compound | Silica                | 60676-86-0  | 85.00%      | 29.4592%          |
|               | Epoxy Resin           | 85954-11-6  | 8.50%       |                   |
|               | Phenol Resin          | 29690-82-2  | 6.00%       |                   |
|               | Carbon Black          | 1333-86-4   | 0.50%       |                   |
| Plating       | Tin                   | 7440-31-5   | 100.00%     | 3.7561%           |

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, It is for guidance only and we cannot guarantee to its accuracy or completeness.